

#### Part Number: XZUR55W-1

3.2mmx1.6mm SMD CHIP LED LAMP

#### **Features**

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

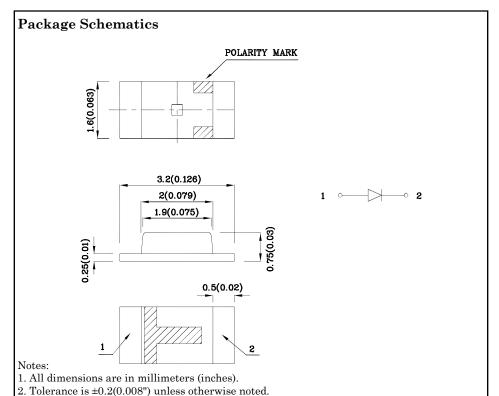
ullet Package : 2000pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant







**Absolute Maximum Ratings** UR Unit (T<sub>A</sub>=25°C) (GaAsP/GaP)  $V_{\rm R}\,$ V Reverse Voltage 5 Forward Current  $I_{\rm F}$ 30 mA Forward Current (Peak) 1/10 Duty Cycle 160 mA  $i_{FS}$ 0.1ms Pulse Width Power Dissipation  $P_{\mathrm{D}}$ 75 mWOperating Temperature  $T_{\rm A}$  $-40 \sim +85$  ${}^{\rm o}{\rm C}$ Storage Temperature Tstg  $-40 \sim +85$ 

Operating Characteristics (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λΡ	627	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20\text{mA})$	λD	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$\triangle \lambda$	45	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

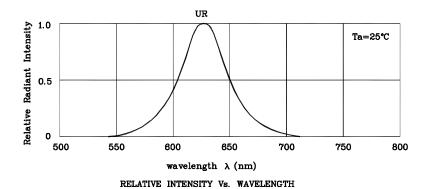
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous\\ Intensity\\ (I_F=20mA)\\ mcd \end{array}$		Wavelength nm $\lambda P$	Viewing Angle 20 1/2
				min.	typ.		
XZUR55W-1	Red	GaAsP/GaP	Water Clear	8	14	627	120°

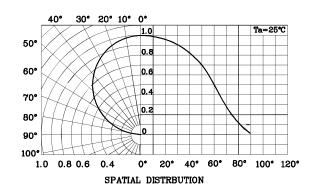
3. Specifications are subject to change without notice.

Apr 11,2011 XDSA1316 V6 Layout: Maggie L.

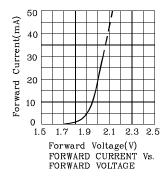


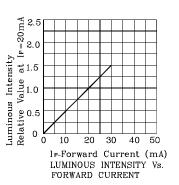


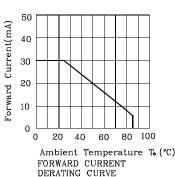


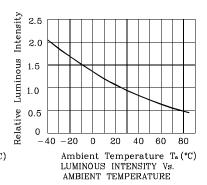


#### **\$** UR



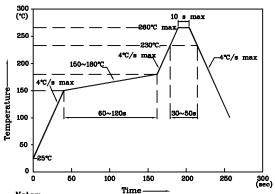






# LED is recommended for reflow soldering and soldering profile is shown below.

# Reflow Soldering Profile for SMD Products (Pb-Free Components)

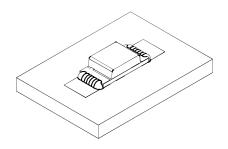


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

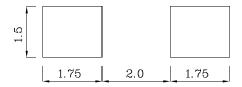




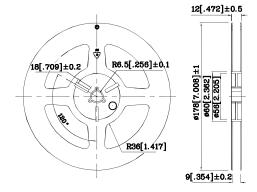
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



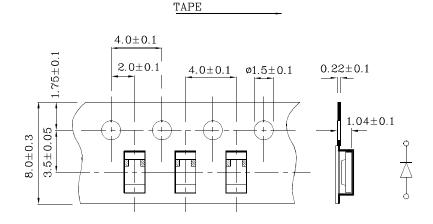
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



# **❖** Reel Dimension



# **❖** Tape Specification (Units:mm)



#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

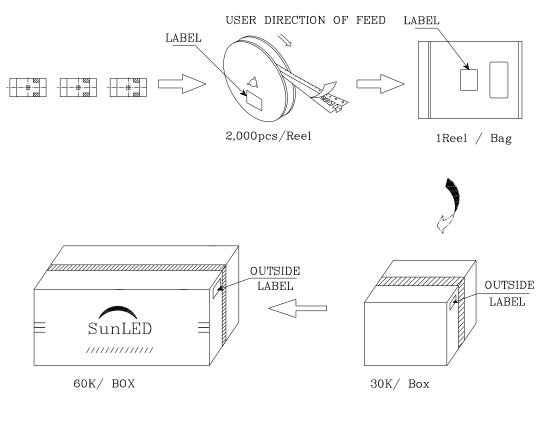
Note: Accuracy may depend on the sorting parameters.

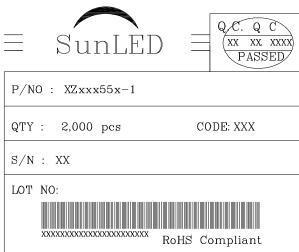
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#### PACKING & LABEL SPECIFICATIONS





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